

Special Issue

Structural Health Monitoring and Their Applications Across Industry

Message from the Guest Editor

Structural health monitoring is used to evaluate the “state” of a structure at every moment during its life. It involves the integration of structure design, sensors, smart materials, data transmission and analysis.

Structural health monitoring is the new way of non-destructive evaluation, however these techniques have not been widely used in practical engineering due to wiring problems associated with large-scale structural health monitoring. The aim of this Special Issue is for researchers to gain an in-depth understanding of structural health monitoring techniques and analyze the different applications through various cross-industry case studies, including oil and gas, rail, nuclear, aerospace, thermal and renewable energy, highlighting the latest developments on testing methods and sensor development and promoting more accurate results for defect identification

Guest Editor

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